



DMG4N60SJ3

N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BV _{DSS} (@ T _J Max) | R _{DS(ON)} Max | I _D T _C = +25°C | |
|--|------------------------------|--|--|
| 650V | 2.5Ω @ V _{GS} = 10V | 3.0A | |

Features and Benefits

- Low On-Resistance
- High BV_{DSS} Rating for Power Application
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Motor Control
- Backlighting
- DC-DC Converters
- **Power Management Functions**

Mechanical Data

- Case: TO251 and TO251 (Type TH)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.33 grams (Approximate)

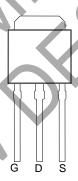




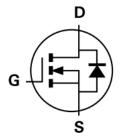




Bottom View



Top View Pin Configuration



Internal Schematic

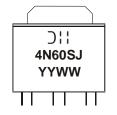
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|-------------|-----------------|----------------|
| DMG4N60SJ3 | TO251 | 75 pieces/Tube |
| DMG4N60SJ3 | TO251 (Type TH) | 75 pieces/Tube |

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>
 4. For packaging details, see http://www.diodes.com/products/packages.html.

Marking Information



☐ FManufacturer's Marking 4N60SJ = Product Type Marking Code YYWW = Date Code Marking YY or YY = Last Two Digits of Year (ex: 16 = 2016) WW or WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

| Characteristic | | | Symbol | Value | Units |
|---|----------------|------------|-----------------|-------|-------|
| Drain-Source Voltage | | | V_{DSS} | 600 | V |
| Gate-Source Voltage | | | V_{GSS} | ±30 | V |
| Continuous Drain Current (Note 5) V _{GS} = 10V | I _D | 3.0 1.9 | А | | |
| Maximum Body Diode Forward Current (Note 5) | I _S | 6.0 | Α | | |
| Pulsed Drain Current (10μs pulse, Duty Cycle = 1%) | | | I _{DM} | 6.0 | Α |
| Avalanche Current, L = 60mH (Note 7) | | | I _{AS} | 1.7 | Α |
| Avalanche Energy, L = 60mH (Note 7) | | | E _{AS} | 90 | mJ |

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Units |
|--|---|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 5) | $T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$ | P _D | 41 16 | W |
| Thermal Resistance, Junction to Ambient (Note 6) | | R _{OJA} | 47 | °C/W |
| Thermal Resistance, Junction to Case (Note 5) | | R _{eJC} | 3.0 | C/VV |
| Operating and Storage Temperature Range | | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | Cumbal | Min | Tym | May | Allmit | Toot Condition | |
|---|---------------------|----------|------------|-----|--------|--|--|
| | Symbol | Min | Тур | Max | Unit | Test Condition | |
| OFF CHARACTERISTICS (Note 8) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 600 | | _ | V | $V_{GS} = 0V, I_D = 250\mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | | 1 | μΑ | $V_{DS} = 600V, V_{GS} = 0V$ | |
| Gate-Source Leakage | IGSS | _ | _ ` | 100 | nA | $V_{GS} = \pm 30V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 8) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | 2.5 | + | 4.5 | V | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | | 2.0 | 2.5 | Ω | $V_{GS} = 10V, I_{D} = 2A$ | |
| Diode Forward Voltage | V_{SD} | _ | 3 – | 1.4 | V | $V_{GS} = 0V, I_{S} = 1A$ | |
| DYNAMIC CHARACTERISTICS (Note 7) | | | | | | | |
| Input Capacitance | C _{iss} | _ | 532 | _ | | V 25V 6 4 0MHz | |
| Output Capacitance | Coss | Y | 47 | _ | pF | $V_{DS} = 25V, f = 1.0MHz,$ $V_{GS} = 0$ | |
| Reverse Transfer Capacitance | Crss | <u> </u> | 4 | _ | | | |
| Gate Resistance | R_G | _ | 3.3 | _ | Ω | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$ | |
| Total Gate Charge (V _{GS} = 10V) | Qg | _ | 14.3 | _ | | $V_{DD} = 480V, I_D = 4A,$ $V_{GS} = 10V$ | |
| Gate-Source Charge | Q _{gs} | _ | 3.3 | _ | nC | | |
| Gate-Drain Charge | Q_{gd} | _ | 6.9 | _ | | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 14 | _ | | $V_{DD} = 300V, R_G = 25\Omega, I_D = 4A,$ $V_{GS} = 10V$ | |
| Turn-On Rise Time | t _R | 1 | 34 | _ | no | | |
| Turn-Off Delay Time | t _{D(OFF)} | _ | 32 | _ | ns | | |
| Turn-Off Fall Time | t _F | _ | 25 | _ | | | |
| Body Diode Reverse Recovery Time | t _{RR} | _ | 229 | _ | ns | $dI/dt = 100A/\mu s$, $V_{DS} = 100V$, | |
| Body Diode Reverse Recovery Charge | Q _{RR} | _ | 1564 | _ | nC | I _F = 4A | |

Notes:

- 5. Device mounted on infinite heatsink.
- 6. Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper pad layout.
- Guaranteed by design. Not subject to production testing.
 Short duration pulse test used to minimize self-heating effect.



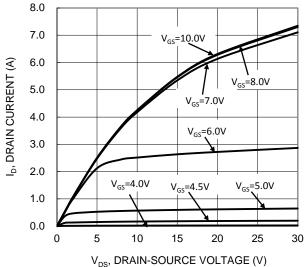


Figure 1. Typical Output Characteristic

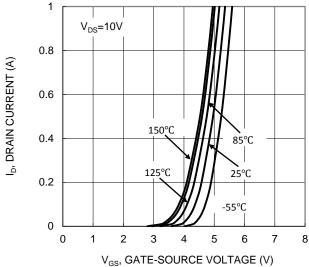


Figure 2. Typical Transfer Characteristic

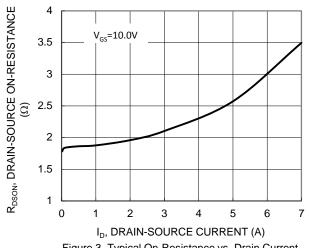


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

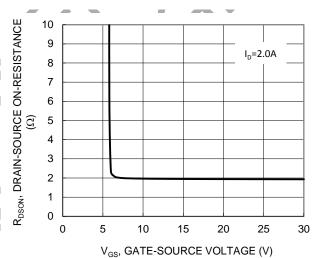


Figure 4. Typical Transfer Characteristic

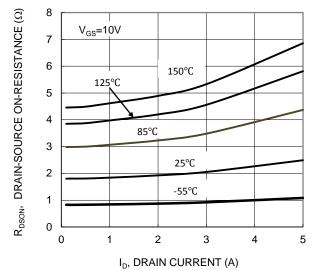


Figure 5. Typical On-Resistance vs Drain Current and Temperature

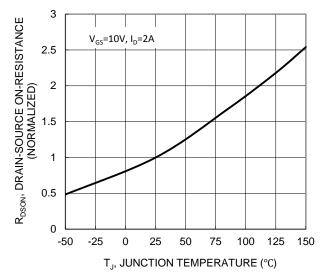


Figure 6. On-Resistance Variation with Temperature



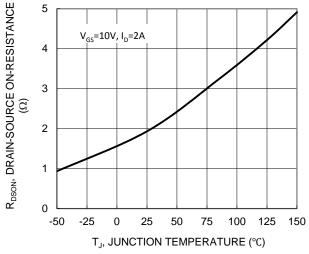


Figure 7. On-Resistance Variation with Temperature

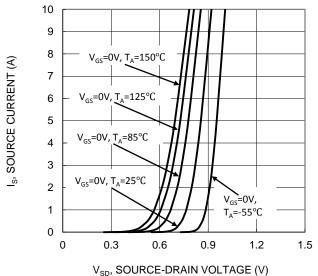
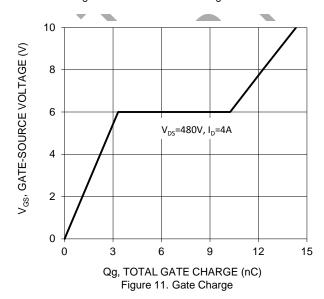
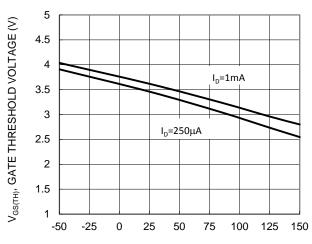


Figure 9. Diode Forward Voltage vs. Current





 $T_{\rm J}$, JUNCTION TEMPERATURE (°C) Figure 8. Gate Threshold Variation vs. Junction Temperature

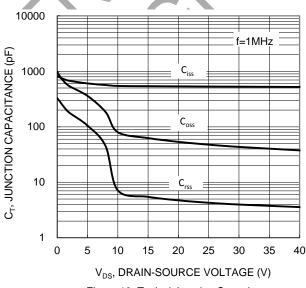
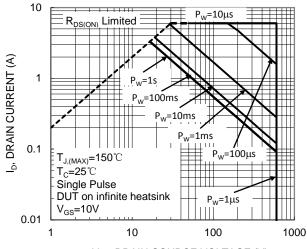
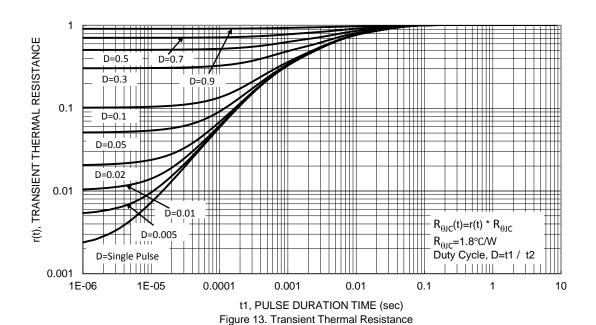


Figure 10. Typical Junction Capacitance



V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area

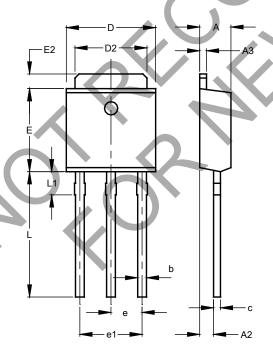




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: TO251



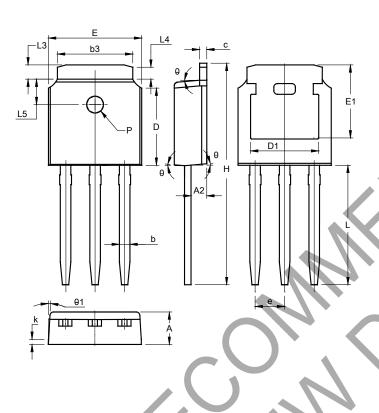
| TO251 | | | | | |
|----------------------|------|------|--|--|--|
| Dim | Min | Max | | | |
| Α | 2.20 | 2.40 | | | |
| A2 | 0.95 | 1.15 | | | |
| А3 | 0.45 | 0.55 | | | |
| b | 0.55 | 0.74 | | | |
| С | 0.45 | 0.55 | | | |
| D | 6.45 | 6.75 | | | |
| D2 | 5.20 | 5.40 | | | |
| Е | 5.95 | 6.25 | | | |
| E2 | 0.95 | 1.25 | | | |
| е | 2.24 | 2.34 | | | |
| e1 | 4.43 | 4.73 | | | |
| L | 9.00 | 9.40 | | | |
| L1 | 1.30 | 1.70 | | | |
| All Dimensions in mm | | | | | |



Package Outline Dimensions (continued)

 $\label{prop:package-outlines.html} Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

(2) Package Type: TO251 (Type TH)



| TO251 (Type TH) | | | | | |
|----------------------|----------|--------|-------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 2.20 | 2.40 | 2.30 | | |
| A2 | 0.97 | 1.17 | 1.07 | | |
| b | 0.68 | 0.90 | 0.78 | | |
| b3 | 5.20 | 5.50 | 5.33 | | |
| С | 0.43 | 0.63 | 0.53 | | |
| D | 5.98 | 6.22 | 6.10 | | |
| D1 | 5 | .30 RE | F | | |
| е | 2. | 286 BS | C | | |
| E | 6.40 | 6.80 | 6.60 | | |
| E1 | 4.63 | 5.03 | 4.83 | | |
| Н | 16.22 | 16.82 | 16.52 | | |
| k | 0 | .40 RE | F | | |
| T | 9.15 | 9.65 | 9.40 | | |
| L3 | 0.88 | 1.28 | 1.02 | | |
| L4 | 0.75 REF | | | | |
| L5 | 1.65 | 1.95 | 1.80 | | |
| ΡØ | 1.20 | | | | |
| θ | 5° | 9° | 7° | | |
| θ1 | 5° 9° 7° | | | | |
| All Dimensions in mm | | | | | |



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